

ABSTRACT OF THE DISCLOSURE

A thermally enhanced BGA substrate in which a metal (copper) core has dielectric layers applied to each side thereof and conductive through-core build-up vias are provided. Rigidifying non-conductive dielectric sheets are laminated to the oppositely facing surfaces and then conductive layers are applied to at least one of the rigidifying non-conductive sheets and via connections are made through the dielectric layer(s) to the core conductive layer.

Amendments to the Abstract of the Disclosure:

Please substitute the new Abstract which accompanies this amendment for the abstract presently on file.